

T-3010
Component Lead Tinning Flux

Product Description

Hasaconi T-3010 Component Lead Tinning Flux is a low solid content flux formulated with high purity specialty chemicals for improved activity and surface tension reduction capacities. This flux is halide-free, water-based flux designed for dipping applications on component leads made of nickel-iron (Alloy 42), nickel, and copper. The residue can be easily removed with hot deionised water or soft water at 40 - 50 °C.

Application

T-3010 is specially formulated for dipping and wave applications. A uniform coat of flux is required for consistent and optimum solderability. T-3010 is to be used as received. No dilution is necessary.

Residue Removal

The residue left after soldering is hygroscopic and ionisable. Complete residue removal immediately after soldering is recommended. Removal of the residue can best be achieved with water at a minimum temperature of 40°C, followed by a final deionised water rinse.

Recommended Solvent

No solvent is required.

Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

Storage

Under proper storage condition, T-3010 can be stored for about 6 months.

Packaging

Available in 20kg/carboy.

Specification

Item	Result
State	Liquid
Colour	Colourless
Specific Gravity @ 22°C	1.057 +/- 0.005
<small>JIS Z 3197 8.2.2</small>	
Non-volatile Solid Content (110°C, 3hr)	7.0 +/- 0.5 wt%
<small>IPC-TM-650 2.3.34</small>	
<small>JIS Z 3197 8.1.3</small>	
Halide Content	Not added
<small>JIS Z 3197 8.1.4.2.1</small>	
Water Extract Resistivity	> 1 x 10 ⁴ Ω-cm
<small>JIS Z 3197 8.1.1</small>	
Acid Value Test	46 +/- 3 mg KOH/g flux
<small>IPC-TM-650 2.3.13</small>	
<small>JIS Z 3197 8.1.4.1</small>	
Copper Corrosion Test	Pass
<small>IPC-TM-650 2.6.15</small>	
<small>JIS Z 3197 8.4.1</small>	
Copper Mirror Test	Classified as "M", Pass
<small>IPC-TM-650 2.3.32</small>	
<small>JIS Z 3197 8.4.2</small>	
Flux Activity Classification	ORM0
<small>IPC J-STD-004</small>	
pH	1
Flash Point	None
Spread Factor	> 80% (Brass Plating)
<small>JIS Z 3197 8.3.1.1</small>	> 80% (Copper Plating)
Surface Finish	Shiny

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